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Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.78mm +/-0.10mm
S	0.75mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information	
Series	SMD Comm X8R HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms